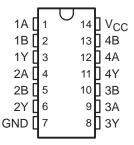
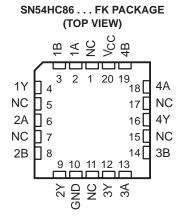
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 10 ns

SN54HC86 . . . J OR W PACKAGE SN74HC86 . . . D, N, NS, OR PW PACKAGE (TOP VIEW)



- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- True Logic



NC - No internal connection

#### description/ordering information

These devices contain four independent 2-input exclusive-OR gates. They perform the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

#### ORDERING INFORMATION

TA	PACKA	GE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC86N	SN74HC86N
		Tube of 50 SN74HC86D		
	SOIC - D	Reel of 2500	SN74HC86DR	HC86
–40°C to 85°C		Reel of 250	SN74HC86DT	
-40 C to 65 C	SOP - NS	Reel of 2000	SN74HC86NSR	HC86
		Tube of 90	SN74HC86PW	
	TSSOP - PW	Reel of 2000	SN74HC86PWR	HC86
		Reel of 250	SN74HC86PWT	
	CDIP – J	Tube of 25	SNJ54HC86J	SNJ54HC86J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC86W	SNJ54HC86W
	LCCC – FK	Tube of 55	SNJ54HC86FK	SNJ54HC86FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



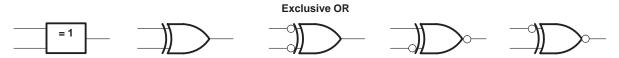
logic level (i.e., A = B).

#### **FUNCTION TABLE** (each gate)

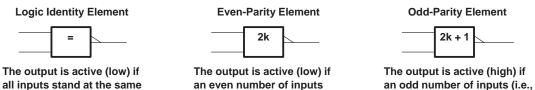
INP	UTS	OUTPUT
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

#### exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an 'HC86 gate in positive logic; negation may be shown at any two ports.



only 1 of the 2) are active.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

(i.e., 0 or 2) are active.

Supply voltage range, V <sub>CC</sub>		0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see	ee Note 1)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CO</sub>	c) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	- 	±25 mA
Continuous current through V <sub>CC</sub> or GND		±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2):	D package	86°C/W
-	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 3)

			S	N54HC8	6	SI	N74HC8	6	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V <sub>CC</sub> = 2 V			0.5			0.5	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35	V
		VCC = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns
		V <sub>CC</sub> = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DARAMETER	TEST COL	IDITIONS	Vaa	T	A = 25°C	;	SN54l	1C86	SN74H	IC86	UNIT
PARAMETER	TEST CON	NDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	$V_I = V_{IH}$ or $V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
ΙĮ	$V_I = V_{CC}$ or 0	·	6 V		±0.1	±100		±1000		±1000	nA
l <sub>CC</sub>	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	6 V			2		40		20	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

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# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vaa	T,	λ = 25°C	;	SN54I	HC86	SN74l	1C86	UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		40	100		150		125	
t <sub>pd</sub>	A or B	Υ	4.5 V		12	20		30		25	ns
			6 V		10	17		25		21	
			2 V		28	75		110		95	
t <sub>t</sub>		Υ	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

#### operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	No load	35	pF

#### PARAMETER MEASUREMENT INFORMATION **From Output** Test Input 50% 50% **Under Test Point** $C_L = 50 pF$ tPLH -<sup>t</sup>PHL (see Note A) $v_{OH}$ In-Phase Output **LOAD CIRCUIT** 10% - tPHL VCC 90% Input 90% **Out-of-Phase** Output **VOLTAGE WAVEFORM VOLTAGE WAVEFORMS INPUT RISE AND FALL TIMES** PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- NOTES: A.  $\text{C}_{\text{L}}$  includes probe and test-fixture capacitance.
  - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
  - C. The outputs are measured one at a time with one input transition per measurement.
  - D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







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#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84046012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84046012A SNJ54HC 86FK	Samples
8404601CA	ACTIVE	CDIP	J	14	1	TBD	TBD SNPB N / A for Pkg Type -55 to 12		-55 to 125	8404601CA SNJ54HC86J	Samples
8404601DA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8404601DA SNJ54HC86W	Samples
JM38510/65202BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65202BCA	Samples
M38510/65202BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65202BCA	Samples
SN54HC86J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SN54HC86J	Samples
SN74HC86D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples
SN74HC86DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples
SN74HC86DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples
SN74HC86DT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples
SN74HC86N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC86N	Samples
SN74HC86NE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC86N	Samples
SN74HC86NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples
SN74HC86NSRE4	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples
SN74HC86NSRG4	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples
SN74HC86PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples



### PACKAGE OPTION ADDENDUM

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC86PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC86	Samples
SNJ54HC86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84046012A SNJ54HC 86FK	Samples
SNJ54HC86J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	8404601CA SNJ54HC86J	Samples
SNJ54HC86W	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8404601DA SNJ54HC86W	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN54HC86, SN74HC86:

Catalog: SN74HC86

Automotive: SN74HC86-Q1, SN74HC86-Q1

Military: SN54HC86

#### NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 8-Nov-2018

#### TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All ulmensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC86DT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC86PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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\*All dimensions are nominal

7 III GITTIOTIOTOTIO GITO TIOTITIGA							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC86DR	SOIC	D	14	2500	333.2	345.9	28.6
SN74HC86DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74HC86DT	SOIC	D	14	250	210.0	185.0	35.0
SN74HC86PWR	TSSOP	PW	14	2000	367.0	367.0	35.0

# FK (S-CQCC-N\*\*)

### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



#### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# W (R-GDFP-F14)

### CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# D (R-PDSO-G14)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
  - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



# PW (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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